



1 NOTE:
020122MR008□□25ZA

- Selective plating
 *S1,-05u" Min. gold in contact area/
 100u" Min. Tin in solder area.
 *S2,-Gold flash in contact area/
 100u" Min. Tin in solder area.
 *S3,-10u" Min. gold in contact area/
 100u" Min. Tin in solder area.
 *S4,-15u" Min. gold in contact area/
 100u" Min. Tin in solder area.
 *S5,-30u" Min. gold in contact area/
 100u" Min. Tin in solder area.
 *S6,-50u" Min. gold in contact area/
 100u" Min. Tin in solder area.

6	SHELL	Brass	——	NICK PLATED
5	SHELL	Brass	——	NICK PLATED
4	SHELL	Brass	——	NICK PLATED
3	TERMINAL	Pho.Bronze	——	GOLD/TIN
2	BACK-CAP	LCP	BLACK	UL 94V-0
1	HOUSING	LCP	BLACK	UL 94V-0
NO.	DESCRIPTION	MATERIAL	COLOR	REMARK

SUYIN
CONNECTOR

CUSTOMER COPY TITLE: USB Series A Type Dual Port Dip Type

ECN (DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED	APPRO.	宋權哲	2002/04/02	SCALE	4:1	UNIT	mm	A4	
EC1T-021114-07	C	02/11/14	D1:增加新料號			Angle ±2°	DRAW	薛梅	2002/04/02	PART NO.					
EC1T-020808-07	B	02/08/08	C1:增加偷料孔;C2,C3:修改鐵殼彈片	宋勃逸	宋權哲	30 ~ ±0.50	DESIGN	薛梅	2002/04/02	PART NO. (OLD)					
EC1T-020701-04	A	02/07/01	恢復撕破處 取消撕破處	薛梅	宋權哲	10 ~ 30 ±0.30	CHECK	宋權哲	2002/04/02	DRAWING NO.	D				
				薛梅	周孫宇	~ 10 ±0.15	APPRO.	宋權哲	2002/04/02	ING					